

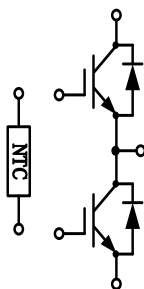
## Half Bridge IGBT Module

### 电气特性:

- 1200V 沟槽栅/场终止工艺
- 低开关损耗
- 正温度系数

### 典型应用:

- 变频器
- UPS
- 伺服
- 逆变器



$V_{CES}=1200V$ ,  $I_{C\ nom}=600A$  /  $I_{CRM}=1200A$

## IGBT, 逆变器 / IGBT, Inverter

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
集电极-发射极电压 Collector-Emitter voltage	$T_{vj}=25^{\circ}C$	$V_{CES}$	1200	V
连续集电极直流电流 Continuous DC collector current	$T_C=100^{\circ}C$ , $T_{vj\ max}=175^{\circ}C$	$I_{C\ nom}$	600	A
集电极重复峰值电流 Repetitive peak collector current	$t_p = 1\ ms$	$I_{CRM}$	1200	A
栅极-发射极电压 Gate emitter voltage		$V_{GE}$	$\pm 20$	V

### 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
集电极-发射极饱和电压 Collector-Emitter saturation voltage	$V_{GE}=15V$ , $I_C=600A$ $T_{vj}=25^{\circ}C$ $V_{GE}=15V$ , $I_C=600A$ $T_{vj}=125^{\circ}C$ $V_{GE}=15V$ , $I_C=600A$ $T_{vj}=150^{\circ}C$	$V_{CE\ sat}$		1.78 2.07 2.13	2.10	V
栅极-发射极阈值电压 Gate-Emitter threshold voltage	$I_C=mA$ , $V_{GE}=V_{CE}$ , $T_{vj}=25^{\circ}C$	$V_{GEth}$	5.2	5.8	6.4	
栅电荷 Gate charge	$V_{GE}=-15V...+15V$	$Q_G$		5.55		$\mu C$
内部栅极电阻 Internal gate resistor		$R_{Gint}$		1.34		$\Omega$
输入电容 Input capacitance	$f=1MHz$ , $V_{CE}=25V$ , $V_{GE}=0\ V$ $T_{vj}=25^{\circ}C$	$C_{ies}$		47.07		nF

Input capacitance					
反向传输电容 Reverse transfer capacitance		$C_{res}$		2.20	
集电极-发射极截止电流 Collector-emitter cut-off current	$V_{CE}=1200V, V_{GE}=0V$ $T_{vj}=25^{\circ}C$	$I_{CES}$		2	mA
栅极-发射极漏电流 Gate-emitter leakage current	$V_{CE}=0V, V_{GE}=20V$ $T_{vj}=25^{\circ}C$	$I_{GES}$		200	nA
开通延迟时间 Turn-on delay time	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_{don}$		201 238 248	
上升时间 Rise time	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_r$		194 200 202	
关断延迟时间 Turn-off delay time	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_{doff}$		582 647 697	ns
下降时间 Fall time	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_f$		105 138 173	
开通损耗能量（每脉冲） Turn-on energy loss per pulse	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ $di/dt=2379A/\mu s$ ( $T_{vj}=150^{\circ}C$ ) (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{on}$		93.35 119.5 130.1 0	mJ
关断损耗能量（每脉冲） Turn-off energy loss per pulse	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=1.5\Omega$ $dv/dt=3121V/\mu s$ ( $T_{vj}=150^{\circ}C$ ) (电感负载) / (inductive load) $T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{off}$		61.57 71.01 76.53	mJ
短路数据 SC data	$V_{GE}\leq 15V, V_{CC}=800V$ $V_{CEmax}=V_{CES}-L_{sCE}\cdot di/dt$ $t_p\leq 10\mu s, T_{vj}=150^{\circ}C$	$I_{sc}$		3000	A
在开关状态下温度 Temperature under switching conditions		$T_{vj op}$	-40	150	$^{\circ}C$

## 二极管，逆变器 / Diode, Inverter

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
反向重复峰值电压 Repetitive peak reverse voltage	$T_{vj}=25^{\circ}C$	$V_{RRM}$	1200	V
连续正向直流电流 Continuous DC forward current		$I_F$	600	A
正向重复峰值电流 Repetitive peak forward current	$t_p=1ms$	$I_{FRM}$	1200	A

## 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
正向电压 Forward voltage	$I_F=600A, V_{GE}=0V$ $I_F=600A, V_{GE}=0V$ $I_F=600A, V_{GE}=0V$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$V_F$	2.44 2.55 2.50	2.70	V
反向恢复峰值电流 Peak reverse recovery current	$I_F=600A, -di_F/dt=2417A/\mu s$ $V_R=600V$ $V_{GE}=-15V$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$I_{RM}$	144 208 240		A
恢复电荷 Recovered charge	$I_F=600A, -di_F/dt=2417A/\mu s$ $V_R=600V$ $V_{GE}=-15V$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$Q_r$	19.70 51.44 63.30		$\mu C$
反向恢复损耗（每脉冲） Reverse recovered energy	$I_F=600A, -di_F/dt=2417A/\mu s$ $V_R=600V$ $V_{GE}=-15V$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{rec}$	4.79 14.37 17.93		mJ
在开关状态下温度 Temperature under switching conditions		$T_{vj op}$	-40		150	$^{\circ}C$

## 负温度系数热敏电阻 / NTC-Thermistor

### 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
额定电阻值 Rated resistances	$T_c=25^{\circ}C, \pm 5\%$	$R_{25}$		5.0		K $\Omega$
B-值 B-value	$\pm 2\%$	$B_{25/50}$		3375		K

## 模块 / Module

Parameter	Conditions	Symbol	Value			Unit
绝缘测试电压 Isolation test voltage	RMS, f=50Hz, t=1min	$V_{ISOL}$	2500			V
内部绝缘 Internal isolation			$Al_2O_3$			
储存温度 Storage temperature		$T_{stg}$	-40		125	$^{\circ}C$
模块安装的扭矩 Mounting torque for modul mounting		M	3.0		6.0	Nm
重量 Weight		W		343		g

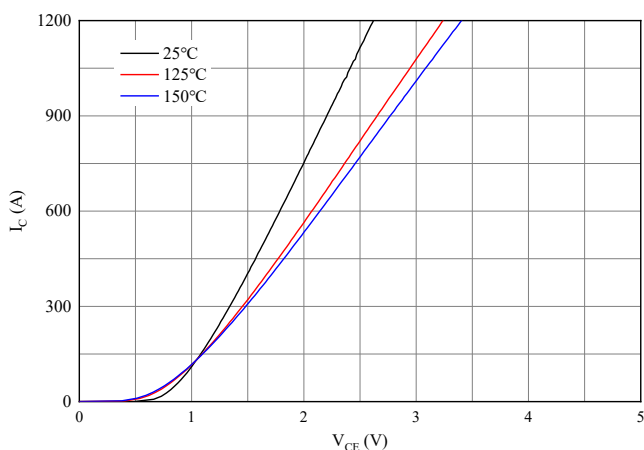


图 1. 典型输出特性 ( $V_{GE}=15V$ )  
Figure 1. Typical output characteristics ( $V_{GE}=15V$ )

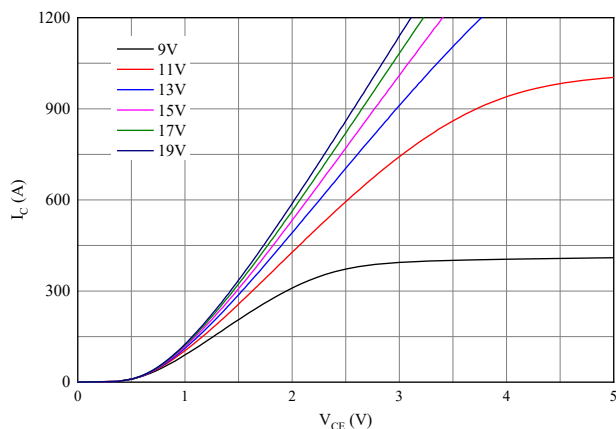


图 2. 典型输出特性 ( $T_{vj}=150^{\circ}C$ )  
Figure 2. Typical output characteristics ( $T_{vj}=150^{\circ}C$ )

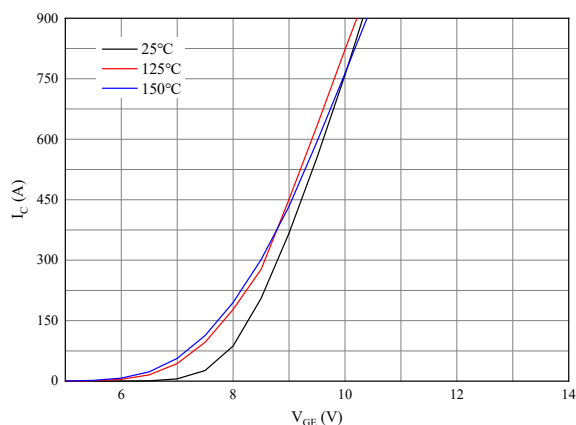


图 3. 典型传输特性 ( $V_{CE}=20V$ )  
Figure 3. Typical transfer characteristic ( $V_{CE}=20V$ )

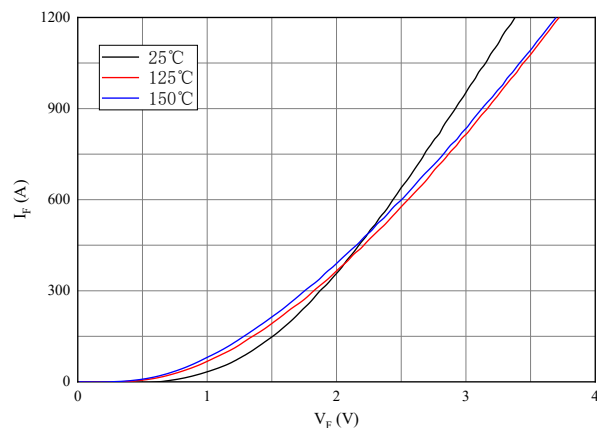


图 4. 正向偏压特性 二极管  
Figure 4. Forward characteristic of Diode

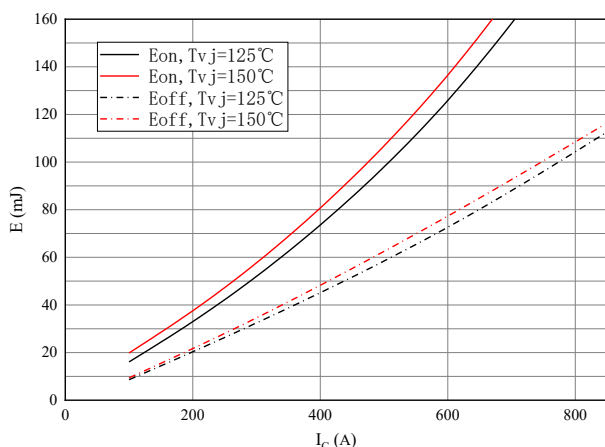


图 5. 开关损耗 逆变器  
Figure 5. Switching losses of IGBT  
 $V_{GE}=\pm 15V$ ,  $R_{Gon}=1.5\Omega$ ,  $R_{Goff}=1.5\Omega$ ,  $V_{CE}=600V$

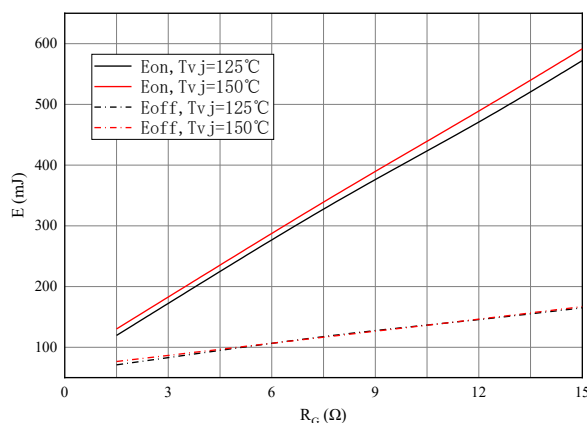


图 6. 开关损耗 逆变器  
Figure 6. Switching losses of IGBT  
 $V_{GE}=\pm 15V$ ,  $I_C=600A$ ,  $V_{CE}=600V$

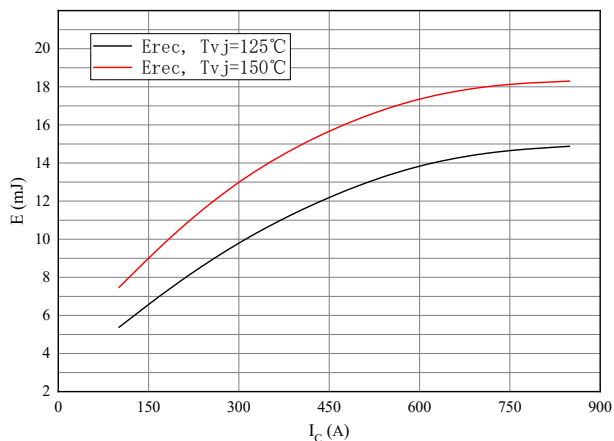


图 7. 开关损耗 二极管

Figure 7. Switching losses of Diode  
 $R_{Gon}=1.5\Omega$ ,  $V_{CE}=600V$

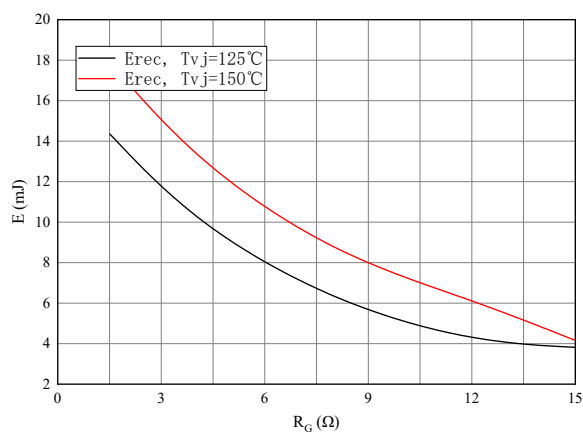


图 8. 开关损耗 二极管

Figure 8. Switching losses of Diode  
 $I_F=600A$ ,  $V_{CE}=600V$

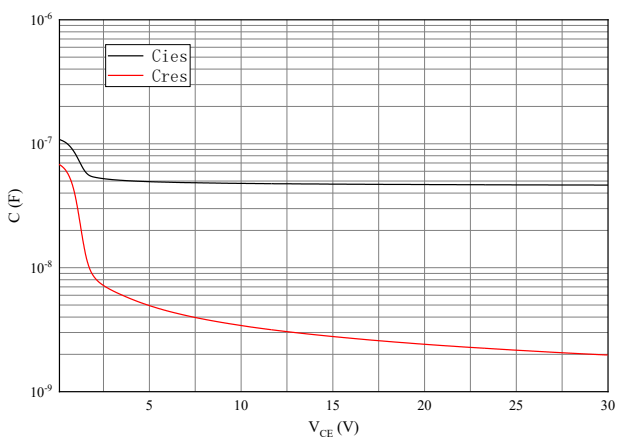


图 9. 电容特性

Figure 9. Capacitance characteristic

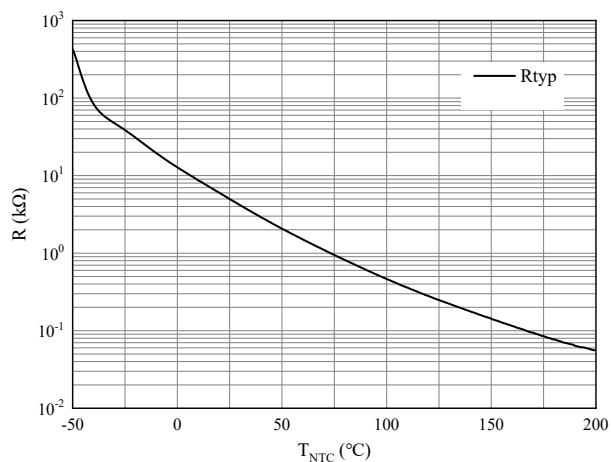
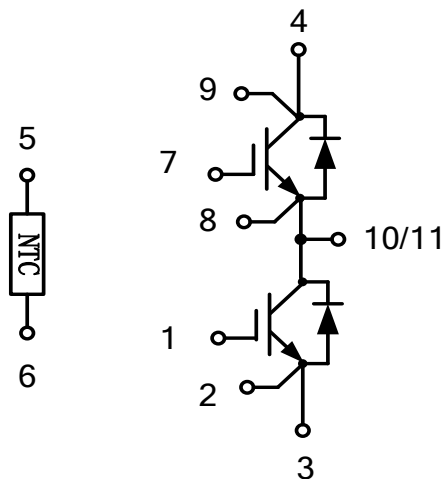


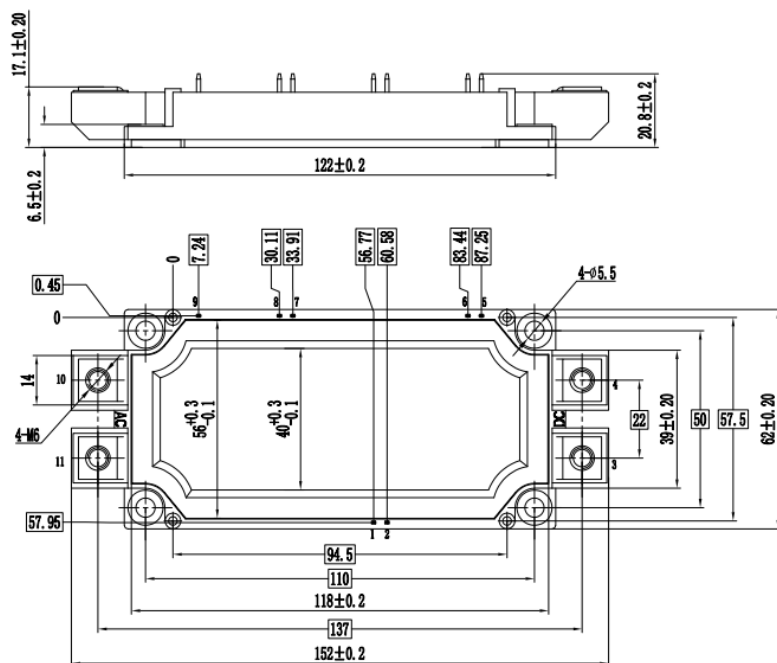
图 10. 负温系数热敏电阻 温度特性

Figure10. NTC-Thermistor-temperaturecharacteristic

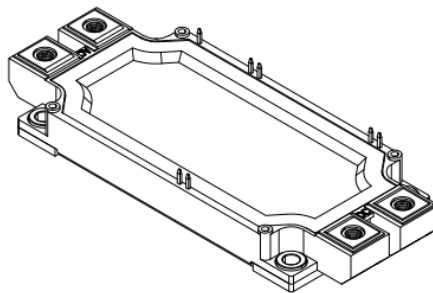
接线图 / Circuit diagram



封装尺寸 / Package outlines



局部视图 I  
比例 5 : 1  
1.15±0.3  
0.8±0.3



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